CLAIM AMENDMENTS

1. (Currently Amended) An electronic device comprising:

an element-carrying-substrate having an electronic element and a first electrode, the first electrode being disposed on a surface of the element-carrying-substrate and having a first area;

a wiring substrate facing the element-carrying-substrate and having a second electrode disposed on a surface of said wiring substrate, the second electrode having a second area and facing the first electrode; and

a coupler disposed between the first electrode and the second electrode, joining the element-carrying-substrate to the wiring substrate, the coupler-having including a resin body with a surface, and an electrically conductive member, and a occupying from 20% to 80% of the surface comprising a of the resin region body and an electrically conductive region electrically connecting the first electrode to the second electrode.

Claim 2 (Cancelled).

- 3. (Currently Amended) The electronic device as claimed in claim 1, wherein the electrically conductive member is a joining metal-and-the electrically conductive region includes the joining metal that is located on the surface of the coupler.
- 4. (Currently Amended) The electronic device as claimed in claim 1, wherein the electrically conductive member comprises a metal powder with a high melting-point and the electroconductive region includes the a joining metal powder that is located on the surface of the coupler film, the metal powder being joined to a the joining metal film.
- 5. (Withdrawn, Currently Amended) The electronic device as claimed in claim 1, wherein the electrically conductive member comprises a metal strip layer joined to a joining metal film, the metal strip layer encircling the resin body as the electrically enductive region.
- 6. (Withdrawn, Currently Amended) The electronic device as claimed in claim 5, wherein the metal strip layer has an opening disposed substantially at a center of the element_carrying_substrate and the wiring substrate.

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- 7. (Currently Amended) The electronic device as claimed in claim 1, wherein the resin body—is comprises a thermosetting resin.
- 8. (Currently Amended) The electronic device as claimed in claim 1, wherein the resin body-is comprises a thermoplastic resin.
- 9. (Currently Amended) A coupler with a spherical shape comprising a blend of a joining metal and a resin, wherein the coupler includes body having a surface comprising and an electrically conductive region formed by the member comprising a blend of a joining metal and a resin region formed by occupying from 20% to 80% of the surface of the resin body.
- 10. (Currently Amended) The coupler as claimed in claim <u>4_9</u>, further comprising a resin body and a metal powder with a high melting point, wherein the metal powder that is located on the surface of the coupler resin body is joined to the joining metal to form the electrically conductive region.

Claims 11 and 12. (Cancelled).

- 13. (Currently Amended) The coupler as claimed in claim 10, wherein the resin body—is comprises a thermosetting resin.
- 14. (Currently Amended) The coupler as claimed in claim 10, wherein the resin body—is comprises a thermoplastic resin.

AMENDMENTS TO THE DRAWINGS

Six sheets of replacement drawings are attached, including Figures 1-17. The replacement drawings conform sectional areas, where present, to cross-hatching requirements of U.S. practice and eliminate solid black regions.

Attachment: Replacement Sheet(s)